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(54) **Title:** LIGHT PIPE STRUCTURE WINDOW FOR LOW PRESSURE THERMAL PROCESSES

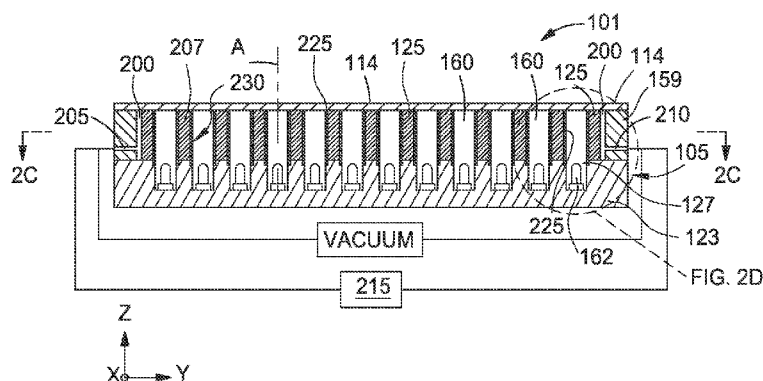


FIG. 2B

(57) **Abstract:** Embodiments disclosed herein relate to a light pipe structure for thermal processing of semiconductor substrates. In one embodiment, a light pipe window structure for use in a thermal process chamber includes a transparent plate, and a plurality of light pipe structures formed in a transparent material that is coupled to the transparent plate, each of the plurality of light pipe structures comprising a reflective surface and having a longitudinal axis disposed in a substantially perpendicular relation to a plane of the transparent plate.